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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg880f64-qfp100t

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (ºC)	Package
EFM32LG395F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG840F64G-E-QFN64	64	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG840F128G-E-QFN64	128	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG840F256G-E-QFN64	256	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG842F64G-E-QFP64	64	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG842F128G-E-QFP64	128	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG842F256G-E-QFP64	256	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG880F64G-E-QFP100	64	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG880F128G-E-QFP100	128	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG880F256G-E-QFP100	256	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG890F64G-E-BGA112	64	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG890F128G-E-BGA112	128	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG890F256G-E-BGA112	256	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG895F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG895F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG895F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG900F256G-E-D1I	256	32	48	1.98 - 3.8	-40 - 85	Wafer
EFM32LG940F64G-E-QFN64	64	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG940F128G-E-QFN64	128	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG940F256G-E-QFN64	256	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG942F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG942F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG942F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG980F64G-E-QFP100	64	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG980F128G-E-QFP100	128	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG980F256G-E-QFP100	256	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG990F64G-E-BGA112	64	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG990F128G-E-BGA112	128	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG990F256G-E-BGA112	256	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG995F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG995F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG995F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120

Module	Configuration	Pin Connections
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	86 pins	Available pins are shown in 5.10.3 GPIO Pinout Overview

3.2.13 EFM32LG842

The features of the EFM32LG842 is a subset of the feature set described in the EFM32LG Reference Manual. The following table describes device specific implementation of the features.

Table 3.13. EFM32LG842 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
TIMER3	Full configuration	TIM3_CC[2:0]
RTC	Full configuration	NA
BURTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx

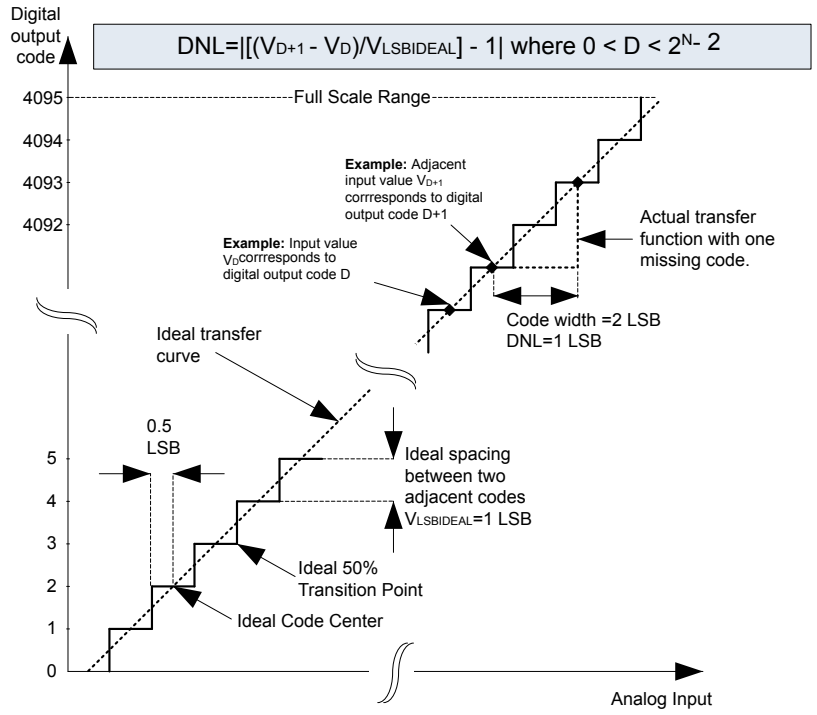

Figure 4.24. Differential Non-Linearity (DNL)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Slew Rate	SR_{OPAMP}	(OPA2)BIASPROG=0xF,(OPA2)HALF-BIAS=0x0, 70 pF load Rising (Simulated at 25 C and VDD=3 V)	—	3.2	—	V/µs
		(OPA2)BIASPROG=0x7,(OPA2)HALF-BIAS=0x1, 70 pF load, Rising (Simulated at 25 Cand VDD=3 V)	—	0.8	—	V/µs
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, 70 pF load, Rising	—	178	—	V/µs
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, 70 pF load, Falling	—	198	—	V/µs
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, 70 pF load, Rising	—	969	—	V/µs
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, 70 pF load, Falling	—	969	—	V/µs
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, 70 pF load, Rising	—	166	—	V/µs
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, 70 pF load, Falling	—	180	—	V/µs
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, 70 pF load, Rising	—	918	—	V/µs
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, 70 pF load, Falling	—	937	—	V/µs
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, 70 pF load, Rising	—	173	—	V/µs
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, 70 pF load, Falling	—	191	—	V/µs
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, 70 pF load, Rising	—	935	—	V/µs
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, 70 pF load, Falling	—	950	—	V/µs
Voltage Noise	N_{OPAMP}	V_{out}=1V, RESSEL=0, 0.1 Hz<f<10 kHz, OPAx-HCMDIS=0	—	101	—	μV_{RMS}
		V_{out}=1V, RESSEL=0, 0.1 Hz<f<10 kHz, OPAx-HCMDIS=1	—	141	—	μV_{RMS}
		Vout=1V, RESSEL=0, 0.1 Hz<f<1 MHz, OPAxHCMDIS=0	—	196	—	μV_{RMS}
		Vout=1V, RESSEL=0, 0.1 Hz<f<1 MHz, OPAxHCMDIS=1	—	229	—	μV_{RMS}
		RESSEL=7, 0.1 Hz<f<10 kHz, OPAxHCM-DIS=0	—	1230	—	μV_{RMS}
		RESSEL=7, 0.1 Hz<f<10 kHz, OPAxHCM-DIS=1	—	2130	—	μV_{RMS}
		RESSEL=7, 0.1 Hz<f<1 MHz, OPAxHCM-DIS=0	—	1630	—	μV_{RMS}
		RESSEL=7, 0.1 Hz<f<1 MHz, OPAxHCM-DIS=1	—	2590	—	μV_{RMS}

4.18 USART SPI

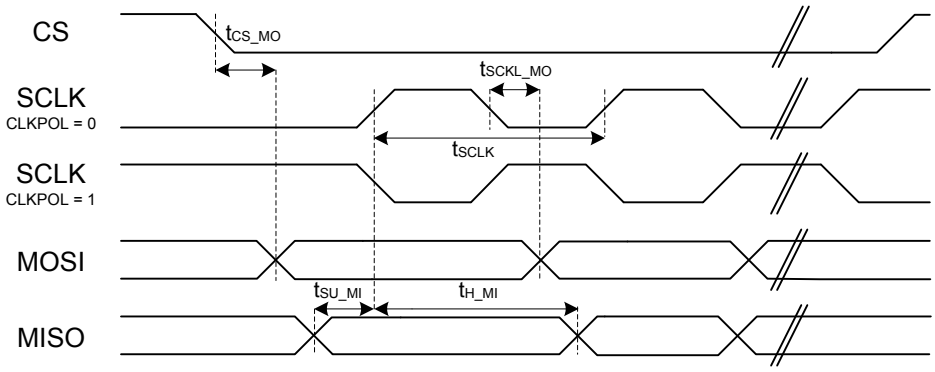

Figure 4.42. SPI Master Timing

Table 4.28. SPI Master Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCLK period	t_{SCLK} [1] [2]		2 × $t_{HFPERCLK}$	—	—	ns
CS to MOSI	t_{CS_MO} [1] [2]		-2.00	—	2.00	ns
SCLK to MOSI	t_{SCLK_MO} [1] [2]		-1.00	—	3.00	ns
MISO setup time	t_{SU_MI} [1] [2]	IOVDD = 3.0 V	36.00	—	—	ns
MISO hold time	t_{H_MI} [1] [2]		-6.00	—	—	ns

Note:
1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)
2. Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

Table 4.29. SPI Master Timing with SSSEARLY and SMSDELAY

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCLK period	t_{SCLK} [1] [2]		2 × $t_{HFPERCLK}$	—	—	ns
CS to MOSI	t_{CS_MO} [1] [2]		-2.00	—	2.00	ns
SCLK to MOSI	t_{SCLK_MO} [1] [2]		-1.00	—	3.00	ns
MISO setup time	t_{SU_MI} [1] [2]	IOVDD = 3.0 V	-32.00	—	—	ns
MISO hold time	t_{H_MI} [1] [2]		63.00	—	—	ns

Note:
1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)
2. Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

QFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3		TIM0_CDTI0 #0		LES_ALTEX2 #0 ETM_TD1 #3
5	PA4		TIM0_CDTI1 #0		LES_ALTEX3 #0 ETM_TD2 #3
6	PA5		TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
10	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
11	PC2	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
12	PC3	ACMP0_CH3DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
13	PC4	ACMP0_CH4 OPAMP_P0	TIM0_CDTI2 #4 LE-TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
14	PC5	ACMP0_CH5 OPAMP_N0	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
15	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
16	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
17	PA8		TIM2_CC0 #0		
18	PA9		TIM2_CC1 #0		
19	PA10		TIM2_CC2 #0		
20	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0 / OPAMP_OUT0	TIM1_CC2 #3 LE-TIM0_OUT0 #1	I2C1_SDA #1	
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
25	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US2_TX	PC2	PB3						USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.4.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32LG290 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.12. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	—	—	—	—	—	—	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

5.4.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG290 is shown in the following figure.

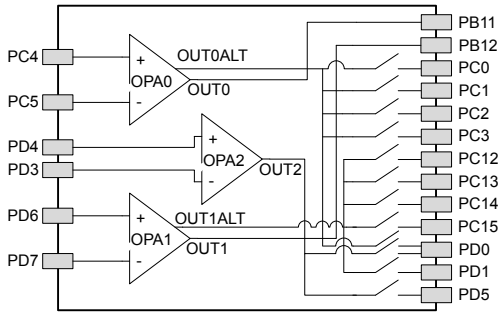

Figure 5.8. Opamp Pinout

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
CMU_CLK0	PA2		PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							
DAC0_OUT1ALT / OPAMP_OUT1ALT					PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
ETM_TCLK	PD7		PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6		PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5		PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

5.7.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG332 is shown in the following figure.

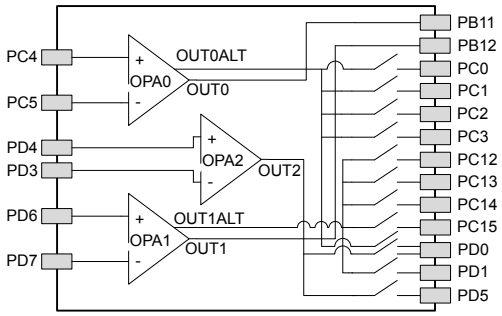

Figure 5.14. Opamp Pinout

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 /OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
ETM_TCLK	PD7		PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6		PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
TIM2_CC1	PA9	PA13	PC9					Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10					Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14	PE0						Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	PE15	PE1						Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	PA15	PE2						Timer 3 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15				UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14				UART0 Transmit output. Also used as receive input in half duplex communication.
U1_RX	PC13	PF11	PB10	PE3				UART1 Receive input.
U1_TX	PC12	PF10	PB9	PE2				UART1 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9	PC15	PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4	PC8	PC14	PB14	PB14		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10	PE12	PB8	PC1		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11	PE13	PB7	PC0		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX	PC1	PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0	PD7					USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH0	PC0							LESENSE channel 0.
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (µm)	Y (µm)	Analog	EBI	Timers	Communica-tion	Other
25	PC3	-2065.0	-1322.6	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0 ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
26	PC4	-2065.0	-1484.3	ACMP0_CH4 OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
27	PC5	-2065.0	-1586.5	ACMP0_CH5 OPAMP_N0	EBI_NANDWEn #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
28	PB7	-2065.0	-1708.6	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
29	PB8	-2065.0	-1830.6	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
30	PA7	-1832.5	-2065.0	LCD_SEG35	EBI_CSTFT #0/1/2			
31	PA8	-1695.5	-2065.0	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
32	PA9	-1558.5	-2065.0	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
33	PA10	-1421.5	-2065.0	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
34	PA11	-1284.5	-2065.0	LCD_SEG39	EBI_HSNC #0/1/2			
35	IOVDD_2	-1147.5	-2065.0	Digital IO power supply 2.				
36	IOVSS_2	-1027.4	-2065.0	Digital IO ground 2.				
37	PA12	-907.2	-2065.0	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
38	PA13	-780.6	-2065.0	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
39	PA14	-654.0	-2065.0	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
40	RESETn	-527.4	-2065.0	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
41	PB9	-401.0	-2065.0		EBI_A03 #0/1/2		U1_TX #2	
42	PB10	-274.5	-2065.0		EBI_A04 #0/1/2		U1_RX #2	
43	PB11	260.7	-2065.0	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LETIM0_OUT0 #1	I2C1_SDA #1	
44	PB12	366.0	-2065.0	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
45	AVSS_2	464.8	-2065.0	Analog ground 2.				
46	AVDD_2	560.5	-2065.0	Analog power supply 2.				

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (µm)	Y (µm)	Analog	EBI	Timers	Communica-tion	Other
67	VDD_DREG	2065.0	-1218.8	Power supply for on-chip voltage regulator.				
68	IOVDD_4	2065.0	-1119.8	Digital IO power supply 4.				
69	DEC_0	2065.0	-1018.9	Decouple output for on-chip voltage regulator.				
70	DEC_1	2065.0	-925.3	Decouple output for on-chip voltage regulator.				
71	DEC_2	2065.0	-847.7	Decouple output for on-chip voltage regulator.				
72	NC	2065.0	-356.4	Do not connect.				
73	IOVSS_4	2065.0	-265.5	Digital IO ground 4.				
74	PE0	2065.0	-181.4		EBI_A07 #0/1/2	TIM3_CC0 #1 PCNT0_S0IN #1	U0_TX #1 I2C1_SDA #2	
75	PE1	2065.0	-93.2		EBI_A08 #0/1/2	TIM3_CC1 #1 PCNT0_S1IN #1	U0_RX #1 I2C1_SCL #2	
76	PE2	2065.0	-1.1	BU_VOUT	EBI_A09 #0	TIM3_CC2 #1	U1_TX #3	ACMP0_O #1
77	PE3	2065.0	91.1	BU_STAT	EBI_A10 #0		U1_RX #3	ACMP1_O #1
78	PE4	2065.0	182.6	LCD_COM0	EBI_A11 #0/1/2		US0_CS #1	
79	PE5	2065.0	302.4	LCD_COM1	EBI_A12 #0/1/2		US0_CLK #1	
80	PE6	2065.0	406.9	LCD_COM2	EBI_A13 #0/1/2		US0_RX #1	
81	PE7	2065.0	519.2	LCD_COM3	EBI_A14 #0/1/2		US0_TX #1	
82	PC8	2065.0	625.8	ACMP1_CH0	EBI_A15 #0/1/2	TIM2_CC0 #2	US0_CS #2	LES_CH8 #0
83	PC9	2065.0	714.3	ACMP1_CH1	EBI_A09 #1/2	TIM2_CC1 #2	US0_CLK #2	LES_CH9 #0 GPIO_EM4WU 2
84	PC10	2065.0	819.1	ACMP1_CH2	EBI_A10 #1/2	TIM2_CC2 #2	US0_RX #2	LES_CH10 #0
85	PC11	2065.0	905.1	ACMP1_CH3	EBI_ALE #1/2		US0_TX #2	LES_CH11 #0
86	PC12	2065.0	1027.7	ACMP1_CH4 DAC0_OUT1ALT #0/ OPAMP_OUT1ALT			U1_TX #0	CMU_CLK0 #1 LES_CH12 #0
87	PC13	2065.0	1131.8	ACMP1_CH5 DAC0_OUT1ALT #1/ OPAMP_OUT1ALT		TIM0_CDTI0 #1/3 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0	U1_RX #0	LES_CH13 #0
88	USB_VREGI_0	2065.0	1237.6	USB input to internal 3.3 V regulator.				
89	USB_VREGI_1	2065.0	1314.6	USB input to internal 3.3 V regulator.				
90	USB_VRE-GO_0	2065.0	1393.0	USB decoupling for internal 3.3 V USB regulator and regulator output.				
91	USB_VRE-GO_1	2065.0	1470.4	USB decoupling for internal 3.3 V USB regulator and regulator output.				

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG28	PD9							LCD segment line 28. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG29	PD10							LCD segment line 29. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG30	PD11							LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12							LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0							LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1							LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2							LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7							LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8							LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9							LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10							LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11							LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH0	PC0							LESENSE channel 0.
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.

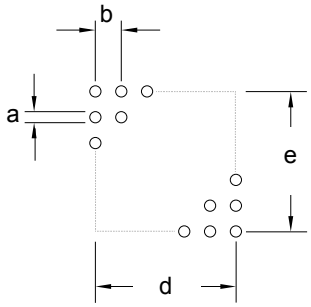

Figure 7.4. BGA120 PCB Stencil Design

Table 7.3. BGA120 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.25
b	0.50
d	6.00
e	6.00

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Pin Definitions.

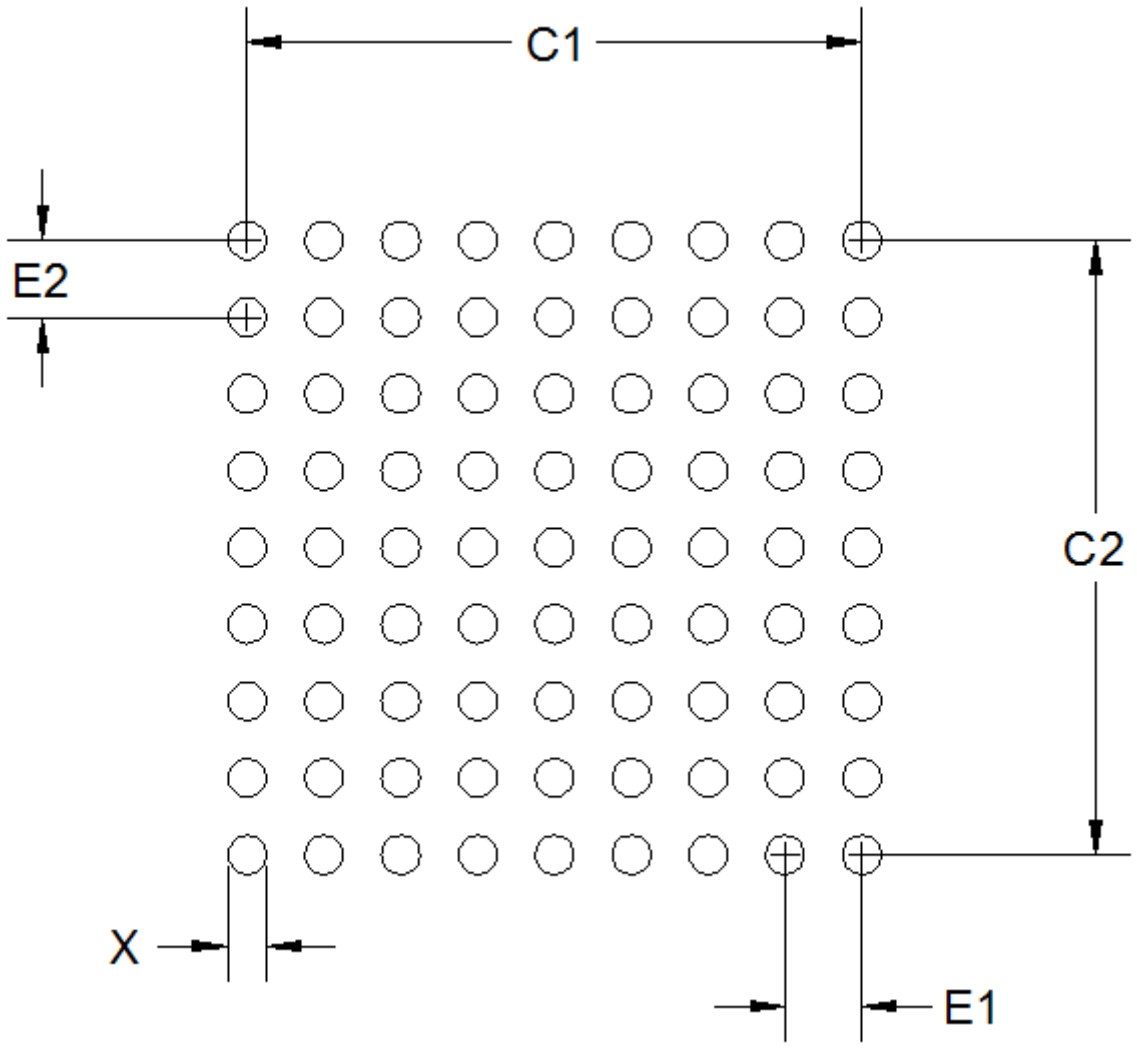

Figure 8.3. CSP81 PCB Solder Mask

Table 8.3. CSP81 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
X	0.26
C1	3.20
C2	3.20
E1	0.40
E2	0.40

14.7 Revision 1.10

June 28th, 2013

This revision applies the following devices:

- EFM32LG230
- EFM32LG232
- EFM32LG280
- EFM32LG290
- EFM32LG295
- EFM32LG330
- EFM32LG332
- EFM32LG380
- EFM32LG390
- EFM32LG395
- EFM32LG840
- EFM32LG842
- EFM32LG880
- EFM32LG890
- EFM32LG895
- EFM32LG940
- EFM32LG942
- EFM32LG980
- EFM32LG990
- EFM32LG995

Updated power requirements in the Power Management section.

For BGA packages, updated PCB Land Pattern, PCB Solder Mask and PCB Stencil Design figures.

Removed minimum load capacitance figure and table. Added reference to application note.

Other minor corrections.

This revision applies the following devices:

- EFM32LG900

December 12th, 2014

Added recommendation to use gold bond wire.